



(11) **EP 2 157 354 A1**

(12) **EUROPEAN PATENT APPLICATION**

(43) Date of publication:
24.02.2010 Bulletin 2010/08

(51) Int Cl.:
F21K 99/00 (2010.01)

(21) Application number: **09165821.1**

(22) Date of filing: **17.07.2009**

(84) Designated Contracting States:
**AT BE BG CH CY CZ DE DK EE ES FI FR GB GR
HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL
PT RO SE SI SK SM TR**
Designated Extension States:
AL BA RS

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(30) Priority: **31.07.2008 US 183501**

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(54) **An illumination apparatus for conducting and dissipating heat from a light source**

(57) An illumination apparatus comprising an optics module wherein a driving circuit may be disposed within the proximal base portion of the optics module. The proximal base portion may further be releasably secured within an independent heat dissipating element. Such an apparatus may be very beneficial in light emitting diode (LED) applications due to its efficient conduction and dissipation of heat away from the LED semiconductor junction. Additionally, a releasable optics module comprising a plurality of LEDs and a driving circuit provides for cost

efficient and environmentally friendly replacement of such a component at the end of its lifespan. The heat dissipating element (e.g. heat sink) may continue to be used, while only the optics module need be replaced or serviced as required. Precious environmental resources may thus be conserved and maintenance costs reduced while concurrently extending the lifespan of such an inventive illumination apparatus.

EP 2 157 354 A1

Description

CROSS REFERENCE TO RELATED APPLICATIONS

[0001] Not applicable.

STATEMENT REGARDING FEDERALLY SPONSORED RESEARCH OR DEVELOPMENT

[0002] Not applicable.

INCORPORATION-BY-REFERENCE OF MATERIAL SUBMITTED ON A COMPACT DISK

[0003] Not applicable.

BACKGROUND OF THE INVENTION

1. Field of the Invention

[0004] The present invention generally relates to conducting and dissipating heat from a light source, more particularly to effectively dissipating heat from a light source via a heat conducting element and an independent heat dissipating element further allowing for economical replacement of an optics module at the end of the lifespan of the light source disposed within the optics module.

2. Background Art

[0005] Over the past century, a variety of different types of light bulbs and other light sources have been developed. The most common type of light source is the incandescent light bulb, in which electric current is passed through a metal filament disposed in a vacuum, causing the filament to glow and emit light. Another common type of light bulb is the fluorescent light.

[0006] The main problem with the standard light bulbs having resistive heating elements (e.g. tungsten) is that such a light source expends more energy as heat than as light. Fluorescent lamps run substantially cooler, but have a substantial lag time between when they are initially turned on and when they actually start emitting light, and are often fairly bulky. Halogen lamps are highly efficient, but need to be handled very carefully and generate a considerable amount of heat when manufactured large enough to provide a usable amount of light, even when powered with low voltage (e.g. 12V).

[0007] The most recent developments in lighting technology involve the expanded use of light emitting diodes (LEDs) that are quite efficient in that they are able to convert virtually all of their supply voltage into light, thereby producing less heat and requiring less overall power consumption. In addition, LEDs may be very small and have an extremely long service life, mainly due to the fact that they operate at cooler temperatures. Compared with a traditional light bulb, an LED lamp may have a

lifespan of about 50 to about 100 times that of the traditional light bulb, and the power consumption of such an LED lamp may be about one third to about one fifth that of the traditional light bulb.

5 [0008] General LED light sources are well known in the art. LEDs are light sources based upon a semiconductor structure, specifically a diode structure, which emit incoherent light (which may be in the ultraviolet, visible, or infrared spectrum) when electrical current is passed through the semiconductor junction. One example of
10 such a light source may include phosphors emitting white light. The original uses of LED light sources were in low-power applications such as indicator lights on instrumentation panels and the like. However, recent developments
15 in LED technology have increased the output power and efficiency of LED sources so that it is now feasible for them to be utilized in traditional lighting applications previously reserved for incandescent, fluorescent, sodium, and known lighting technologies. Commercially available
20 LED light sources surpassed incandescent light sources in terms of efficiency in or around 2002. More recently, commercially available LED light sources have exceeded fluorescent light sources in efficiency. Fluorescent light sources typically exhibit around 100 lumens per Watt
25 (1m/W) efficiency; however LED light sources recently introduced into the market exhibit 130 1m/W efficiency, and there are other LED light sources available and currently under development which exhibit even greater efficiency. Since LEDs have the foregoing advantages, the
30 LED lamp is expected to replace current conventional light bulb technology in the 21st century and become a new light source for illumination while concurrently providing other power-saving and environmentally friendly advantages.

35 [0009] One current drawback with such LED lamps is that when used to replace a conventional incandescent bulb they must have special driving circuits that convert the incoming alternating-current line voltage to the direct-current low voltage needed by the lamp. Such a circuit
40 is normally a small printed-circuit board that is permanently mounted right in the lamp and to which the LED is normally directly soldered. These circuits typically incorporate a transformer to step down the incoming voltage and a rectifier and similar power-supply elements
45 that produce the necessary steady low voltage.

[0010] The problem with such a construction is that the driving circuit itself generates heat, particularly when the LED requires some meaningful amperage, albeit at low voltage. Above a temperature of about 25 degrees Celsius, an LED operates less efficiently and produces less light than at lower temperatures. In particular, as the operating temperature progressively increases above 25 degrees Celsius, the light output of the LED progressively decreases. Since the LED itself is typically carried right
50 on the circuit board, when the circuit elements heat up, the LED is heated. Unfortunately the efficiency of an LED falls off rapidly as it gets hot, and thus known LED lamps tend to dim somewhat after they have been in use for a
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while and their driving circuits have gotten warm. Such a limited conventional design is depicted in Fig. 1, wherein a general light emitting diode 10 integrates several light emitting diodes 20 sealed by a glass cover body 30, which has difficulty in dispersing the heat generated by the light emitting diode 20 during light emission. Such light emitting LED lamps cannot typically operate under normal conditions and tend to have high failure rates.

[0011] As the output power of the commercially available LED light sources continues to improve, it has become necessary to develop methodologies and structures for removing the heat generated by the LED from the LED semiconductor junction. Typical problems caused by heating of the semiconductor junction and surrounding structure are: 1) failures brought on by such occurrences as non-homogenous distribution of the current density over the junction ("current crowding"), which causes a local hot spot in the diode junction leading to early failure due to thermal runaway; 2) nucleation and growth of dislocations in the active region of the diode in which the radiative recombination occurs due to the existence of an existing defect in the semiconductor crystalline structure and which is accelerated by heat; 3) degradation of materials utilized in the LED, such as phosphor, causing loss of efficiency and changes in output color; and 4) electromigration of metal atoms at the metallization layers of the diode causing growth of conductive "whiskers" and early failure. This is not a complete list of the undesired effects brought on by elevated temperatures; it is provided herein simply as a list of exemplary effects.

[0012] In order to manage heat, the prior art has attempted to utilize a variety of heat dissipation techniques, such as the incorporation of heat sinks, heat pipes, fans, water flow, and the like. An LED may be attached to a heat sink via heat conductive adhesive, but if the LED stops working, then the entire component must be discarded, making parts replacement costly. Such LEDs are not exchangeable or serviceable and are therefore rendered disposable and very inefficient.

[0013] Attempts have been made to provide structures for removing heat from the semiconductor junction of LED lamps. See, for example, U.S. Pat. No. 7,226,189 (wherein heat produced is conducted to a heat dissipating device through a metal substrate and then conducted from the heat dissipating device to the light bulb base in an attempt to effectively disperse the heat via structures within the light bulb); U.S. Pat. Appl. No. 2006/0050514 (wherein the base of a bulb is a passive heat sink fittable into a socket); and U.S. Pat. Appl. No. 2006/0061997 (wherein an LED is clamped to a heat sink to permit the LED to be removable and replaceable, thereby making a serviceable LED assembly with an exchangeable LED). The inventions of U.S. Pat. No. 7,226,189 and U.S. Pat. Appl. No. 2006/0050514 are directed at attempts to better conduct heat away from an LED semiconductor junction within an LED lamp via incorporation of heat conductive material within the LED lamp, however, neither reference

discloses a means or additional structure to dissipate heat from the socket of the disclosed LED lamps. U.S. Pat. Appl. No. 2006/0050514 discloses a means of clamping an LED circuit board to a heat sink but fails to disclose a heat sink independent from an optics module, wherein the optics module contains the driving circuit and a plurality of LEDs therein.

[0014] Further consideration must be made in that it is typically necessary for an LED light source to contain some circuitry that will take standard household electrical power and convert it to a voltage and/or waveform that is suitable to drive one or more LEDs. Consequently, a relevant design consideration may be beneficially included to allow for packaging of such circuitry within the LED light source or removable optics module.

[0015] It may be advantageous if the LED lamp has the size and shape of a standard light bulb, including a standard base such as the type of base commonly known as a medium Edison base. However, due to spatial and thermal considerations, many manufacturers have placed the circuitry at a variety of different location, where such designs may alter the size and/or shape of the lamp so that the size and/or shape differ from that of a standard light bulb. For example, the bulb may have a special cylindrical section that is offset from the base and therein contain the circuitry.

[0016] It is also a further desirable consideration to operate the present inventive illumination apparatus and other similar devices at as close to room temperature as possible. A heat conducting element and/or a heat dissipating element may therefore preferably be deployed in such an apparatus in order to remove heat from the LED in an effort to operate the LED as close to room temperature as practicable.

[0017] It is therefore desirable that modern light sources should make use of the currently available LED technology due to the significant benefits that such light sources provide including extremely long life, the ability to control output power and spectrum, and a significant reduction in the amount of electrical energy consumed for equivalent light output power. It is also desirable that such light sources be fabricated from materials that are inexpensive and preferably comprise re-usable, recyclable, or replaceable components so as to require a minimum of new raw material and thus preserve limited natural resources. However, utilizing LED light sources in modern light sources gives rise to the significant challenge of removing the heat from the LED semiconductor junction and surrounding structures. It is therefore desirable, and not currently known in the art, for an illumination apparatus to comprise an optics module containing an integral heat conducting element and an independent heat dissipating element, preferably wherein the integral heat conducting element is a component of an optics module that may be serviced and/or replaced separate and independent from the heat dissipating element so as to be environmentally friendly and lower overall maintenance and/or replacement costs for such present inventive illu-

mination apparatus.

BRIEF SUMMARY OF THE INVENTION

[0018] The present invention solves the afore-mentioned problems in the art by providing an optics module having a pendant body composed of heat conductive material in combination with disposing a driving circuit within the proximal base portion of the optics module. In one such embodiment, the driving circuit may be disposed within a male threaded base at the proximal end of the optics module. Such a location of the driving circuit provides for protection of the driving circuit as well as facilitating the conduction of heat generated by the driving circuit to an independent heat dissipating element. In one embodiment, the heat dissipating element may comprise a heat sink independent of the optics module, into which the optics module may be releasably secured.

[0019] In such a manner, heat may be conducted away from the light source (in the case of a LED light, the heat is conducted away from the semiconductor junction) and transferred from the optics module to a heat dissipating element. Such a structure allows for the service and/or replacement of the optics module (comprising the light emitting diodes and driving circuit) independent of the heat dissipating element (e.g. heat sink) to which the optics module is releasably secured. In accordance with an embodiment of the present invention, recycled aluminum may comprise such thermally conductive and dissipative structures allowing for the use of high efficiency LEDs in illumination apparatus, thus providing for re-use of materials and further resulting in a reduced burden on our limited natural resources. Furthermore, the removable optics module allows for replacement of such a component at the end of its lifespan completely independent of the heat dissipating element, thereby conserving resources and replacement costs throughout the life cycle of such an illumination apparatus.

[0020] The present invention need not be limited to LED light sources or the use of recycled aluminum as the structural material; any other light sources and/or thermally conductive materials may be used in alternate embodiments such as but not limited to laser diodes, incandescent light sources, fluorescent light sources, and alternate thermally conductive materials known in the art.

[0021] In at least one embodiment, the present invention may provide for an illumination apparatus comprising, an optics module comprising; a pendant body, wherein the pendant body comprises a proximal base portion and a distal projection element, a plurality of light emitting diodes disposed on the projection element of the pendant body, a lens cover disposed on the pendant body and encapsulating the plurality of light emitting diodes and the projection element, a driving circuit disposed within the base portion of the pendant body, the base portion defining a cavity in which the driving circuit is disposed, wherein the driving circuit is in electrical communication with the plurality of light emitting diodes, and

a first electrical connector disposed on the proximal surface of the base portion, wherein the first electrical connector is in electrical communication with the driving circuit.

[0022] A further embodiment of the present invention may additionally comprise a heat dissipating element comprising a releasable connection to the base portion of the pendant body, wherein the heat dissipating element is reusable and the releasable connection allows for service or replacement of the optics module independent from the heat dissipating element.

BRIEF DESCRIPTION OF THE DRAWINGS

[0023] A better understanding of the present invention will be realized from the detailed description that follows, taken in conjunction with the accompanying drawings, in which:

[0024] Fig. 1 depicts a front view of the structure of a prior art light emitting diode bulb.

[0025] Fig. 2A depicts a distal perspective view of an embodiment of an illumination apparatus of the present invention.

[0026] Fig. 2B depicts a side view of an embodiment of an illumination apparatus of the present invention.

[0027] Fig. 2C depicts a proximal plan view of an embodiment of an illumination apparatus of the present invention.

[0028] Fig. 2D depicts a distal plan view of an embodiment of an illumination apparatus of the present invention.

[0029] Fig. 3A depicts a distal perspective view of an embodiment of an optics module of the present invention.

[0030] Fig. 3B depicts a proximal perspective view of an embodiment of an optics module of the present invention.

[0031] Fig. 3C depicts a side view of an embodiment of an optics module of the present invention.

[0032] Fig. 3D depicts a diagrammatic cross-sectional view of the optics module of Fig. 3C along its central axis.

[0033] Fig. 3E depicts a distal plan view of an optics module of the present invention.

[0034] Fig. 3F depicts a proximal plan view of an optics module of the present invention.

[0035] Fig. 4A depicts a diagrammatic exploded distal perspective view of an embodiment of an optics module of the present invention.

[0036] Fig. 4B depicts a diagrammatic exploded distal perspective view of another embodiment of an optics module of the present invention.

[0037] Fig. 5A depicts a diagrammatic exploded distal perspective view of an embodiment of an illumination apparatus of the present invention.

[0038] Fig. 5B depicts a diagrammatic cross-sectional view of the illumination apparatus of Fig. 5A along its central axis.

[0039] Fig. 6 depicts a diagrammatic exploded distal perspective view of an embodiment of an illumination ap-

paratus of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

[0040] Although the following detailed description contains many specifics for the purposes of illustration, anyone of ordinary skill in the art will appreciate that many variations and alterations to the following details are within the scope of the invention. Accordingly, the following preferred embodiments of the invention are set forth without any loss of generality to, and without imposing limitations upon, the claimed invention.

[0041] One embodiment of the present inventive illumination apparatus **1000** is illustrated in **Figs. 2A-2D**. As shown in **Figs. 2A-2D**, the illumination apparatus **1000** may generally comprise an optics module **200** that may be releasably secured to a heat dissipating element **300** via a releasable connection. As further depicted, the heat dissipating element **300** may comprise a plurality of radially projecting fins **310**. The Figures also illustrate a lens cover **210** which may encapsulate and enclose other functional components of the optics module **200** there under.

[0042] The illumination apparatus **1000** of the present invention provides a long lasting, energy efficient light source. Additionally, the releasable connection between the optics module **200** and the heat dissipating element **300** allows for service and replacement of an optics module **200** as necessary, while the independent heat dissipating element **300** may remain behind and be re-used with a new or repaired optics module **200**. By separating the optics module **200** and heat dissipating element **300**, the user may conserve resources and replacement costs throughout the life cycle of such an illumination apparatus **1000** since the original heat dissipating element **300** may be continuously re-used.

[0043] **Figs. 3A-3F** depict a variety of views of an embodiment of an optics module **200** of the present invention. The foundation of the optics module **200** may comprise a proximal base portion **230** and a distal projection element **240** encapsulated by a lens cover **210**. The manner in which the lens cover **210** is attached to the pendant body **220** is not critical to the present invention and may comprise any means known in the art including but not limited to a friction fit, snap fit, threading, adhesive, bonding, and the like. The elements of the optics module **200** disposed beneath the lens cover **210** are better illustrated in the cross-sectional view provided in **Fig. 3D**. The projection element **240** may comprise any shape or configuration known within the art, and in a preferred embodiment the projection element **240** may comprise a triangular cross section, as shown in **Figs. 4A-4B**. A plurality of light emitting diodes (LEDs) **250** may be disposed about the surface of the projection element **240**. The manner of attaching the plurality of LEDs **250** to the projection element **240** is not critical to the present invention and any such methods or structures known within the art may be used including but not limited to mechanical

means, chemical means, and the like. In a preferred embodiment, the plurality of LEDs **250** may comprise three independent planar light emitting modules (see **Figs. 4A-4B**). The lens cover **210** may then encapsulate and protect the light emitting components of the optics module **200** disposed there below.

[0044] The base portion **230** of the optics module **200** may comprise a releasable connection at the proximal end of the optics module **200** for securing the optics module **200** to the heat dissipating element **300**. The releasable connection may include but is not limited to a threaded connection (as shown throughout **Figs. 3A-6**), a friction fit connection, a post and groove connection, or any other light fixture connections known within the art. Additionally, the base portion **230** may be comprised of thermally conductive material to assist in conducting heat away from the driving circuit, as discussed below.

[0045] As shown in **Figs. 3B, 3D, and 3F**, the base portion **230** may define a cavity **293** accessible through the proximal surface of the base portion **230** wherein a driving circuit **280** may be disposed. A retention member **294**, as seen in **Fig. 3D**, may be incorporated to assist in maintaining the driving circuit **280** within the cavity **293**. The retention member **294** is not essential to the invention and may comprise any such structures known within the art including but not limited to a leaf spring (as shown) and the like. A first electrical connector **292** may be disposed on the proximal surface of the base portion **230**, wherein the first electrical connector **292** is in electrical communication with the driving circuit **280**. **Figs. 3B, 3D, and 3F** depict the first electrical connector as a button style connector, however, within the scope of the present invention the first electrical connector **292** may comprise any connector type known within the art including but not limited to a button style electrical connector, a leaf spring electrical connector, a coil spring electrical connector, and the like. The first electrical connector **292** may be disposed across the opening of the cavity **293** to assist in forming the electrical connection with the driving circuit **280** and to further assist in physically maintaining the driving circuit **280** within the cavity **293**. However, such a position of the first electrical connector **292** is not essential and a retention member **294** may be used alone to maintain the driving circuit **280** within the cavity **293** if the first electrical connector **292** is not disposed across the mouth of the cavity **293**.

[0046] A channel **289**, as shown in **Figs. 3B, 3D, and 3F**, may be defined by the base portion **230** of the pendant body **220** and such a channel **289** may extend from the distal surface of the base portion **230** to the proximal surface of the base portion **230**. The channel **289** may assist in allowing the plurality of LEDs **250** to be in electrical communication with the driving circuit **280**. Electrical wiring or any other manner of electrical connection known within the art may be used to connect the plurality of LEDs **250** to the driving circuit **280**. In a preferred embodiment, electrical wiring or any other manner of establishing an electrical connection known within the art may

connect with the plurality of LEDs **250**, pass from the distal surface of the base portion **230** through the channel **289** to the proximal surface of the base portion **230**, enter the mouth of the cavity **293**, and then be electrically connected to the driving circuit **280**.

[0047] As depicted in **Fig. 4A**, the optics module **200** may further comprise a first contact board **290** that may be disposed on the proximal surface of the base portion **230** and may further serve to protect and maintain the driving circuit **280** within the cavity **293**. When a first contact board **290** is used, the first electrical connector **292** may be disposed upon the first contact board **290** wherein the first electrical connector **292** remains in electrical communication with the driving circuit **280**. The contact board **290** may be secured in place immediately adjacent the proximal surface of the base portion **230** via at least one fastener member **295**.

[0048] The at least one fastener member **295** may comprise any means of contact board **290** fixation known within the art including but not limited to a screw, a rivet, an adhesive, a bonding material, and the like. In the embodiment shown in **Fig. 4A**, the at least one fastener member **295** is depicted as a threaded screw passing through the first contact board **290** and being secured into the proximal surface of the base portion **230**. In an alternative embodiment, as shown in **Fig. 4B**, the driving circuit **280** may be integral with the first electrical connector **292** disposed thereon and may further include alternate embodiments with or without a first contact board **290** on which the first electrical connector **292** may be disposed.

[0049] **Fig. 5A** depicts an illumination apparatus **1000** of the present invention, wherein a first embodiment of the heat dissipating element **300** is shown. The heat dissipating element **300** may primarily function to transport heat away from the optics module **200** and may also serve to provide the illumination apparatus **1000** with an electrical connection to an outside power source. To provide an electrical connection, the heat dissipating element **300** may comprise a second contact board **296** on which a second electrical connector **297** may be disposed. **Fig. 5A** illustrates the second electrical connector **297** as a spring style connector. However, within the scope of the present invention the second electrical connector **297** may comprise any connector type known within the art including but not limited to a button style electrical connector, a leaf spring electrical connector, a coil spring electrical connector, and the like. When the releasable connection is fully established between the optics module **200** and the heat dissipating element **300**, the first electrical connector **292** of the optics module **200** will be in both physical and electrical communication with the second electrical connector **297** of the heat dissipating element **300**.

[0050] The second contact board **296** may further comprise at least one fixation element **298**. The at least one fixation element **298** may assist in physically maintaining the second contact board **296** within the heat dissipating

element **300** and may also provide a ground for the circuit to the heat dissipating element **300**. **Fig. 5A** depicts the at least one fixation element **298** as four tabs extending from the second contact board **296**. In one such embodiment, as the male threading about the base portion **230** is screwed into the female threading within the heat dissipating element **300**, the second contact board **296** may be disposed therebetween and be driven deeper within the heat dissipating element **300** with the four tab fixation elements **298** retaining the second contact board **296** therein. The four tab fixation elements **298**, being in physical communication with the heat dissipating element **300** may further serve to provide a ground for the electrical circuit.

[0051] **Fig. 5B** depicts a cross-sectional view of the embodiment of **Fig. 5A**. When the releasable connection between the optics module **200** and the heat dissipating element **300** is established, the second contact board **296** may be compressed within the heat dissipating element **300**. In this position, as shown, the first electrical connector **292** (button style contact) is in physical and electrical communication with the second electrical connector **297** (spring style contact). An external electrical connector **301** may provide an electrical connection to a power source external to the illumination apparatus **1000**. The external electrical connector **301** may comprise any form of connector known within the art including but not limited to one or more terminals (as shown in **Figs. 5A-5B**), a wiring connection that may be soldered, bonded, adhered, or mechanically fastened in position, and the like.

[0052] **Fig. 6** illustrates an embodiment of the illumination apparatus **1000** of the present invention wherein the at least one fixation element **298** comprises two mechanical fasteners used to secure the second contact board **296** within the heat dissipating element **300**. The at least one fixation element **298** may comprise any form of fixation known within the art including but not limited to friction fit tabs (see **Fig. 5A**), mechanical fasteners such as screws or rivets (see **Fig. 6**), chemical fasteners such as epoxies, adhesives and other bonds, and the like. A fixation element **298** having conductive properties may also serve as a ground for the electrical circuit to the heat dissipating element **300**.

[0053] The heat dissipating element **300** may comprise a variety of configurations. The plurality of radially projecting fins **310** may be curved (as shown in **Figs. 2A-2C** and **5**), straight, or any other heat dissipating configurations known within the art. The heat dissipating element **300** may further comprise a releasable connection with the optics module **200**, thereby allowing for removal of the optics module **200** from the heat dissipating element **300** when maintenance, repair and/or replacement are required. The releasable connection may include but is not limited to a threaded connection (as shown in **Figs. 5A-6**), a friction fit connection, and any other light fixture connections known within the art. The heat dissipating element **300** and the pendant body **220** may preferably

be composed of extruded aluminum or copper. However, both the heat dissipating element **300** and the pendant body **220** may alternatively and respectively be made of any other suitable material or materials that are thermally conductive, and any combinations thereof.

[0054] In use within a preferred embodiment, as best shown in **Figs. 3D** and **5B**, the optics module **200** may have a releasable physical connection with the heat dissipating element **300** via complimentary male/female threading or any other such connection known within the art. With the primary heat dissipating element **300** being disposed external to the optics module **200**, the optics module **200** may be replaced or repaired independent of the heat dissipating element **300** via such a releasable connection. As shown in **Fig. 3D**, the light source, such as a plurality of LEDs **250**, may be disposed on the projection element **240** of the pendant body **220**. Wiring or any other form of electrical connection known within the art may then pass through a channel **289** disposed within the base portion **230** of the pendant body **220** extending from the distal surface of the base portion **230** to the proximal surface of the base portion **230**. The wiring or other electrical connection may then enter the mouth of a cavity **293** on the proximal surface of the base portion **230**. Within the cavity **293**, the wiring or other electrical connection may form an electrical connection with the driving circuit **280** disposed therein. The driving circuit **280** may then be in electrical communication with the first electrical connector **292** disposed on the proximal surface of the base portion **230**. When the releasable connection between the optics module **200** and the heat dissipating element **300** is fully established, as shown in **Fig. 5B**, the first electrical connector **292** of the optics module **200** may be in both physical and electrical communication with the second electrical connector **297** disposed on the second contact board **296** of the heat dissipating element **300**. The second contact board **296** may further comprise at least one fixation element **298** to physically maintain the second contact board **296** within the heat dissipating element **300**, and may further provide a means for grounding the circuit to the heat dissipating element **300**. The second electrical connector **297** may then be in electrical communication with an external electrical connector **301**, thereby connecting the illumination apparatus **1000** to an external power source.

[0055] The present invention makes use of the currently available LED technology due to the significant benefits that such light sources provide including extremely long life, the ability to control output power and spectrum, and a significant reduction in the amount of electrical energy consumed for equivalent light output power. Many of the structures of the illumination apparatus may be fabricated from materials that are inexpensive and preferably comprise re-usable, recyclable, or replaceable components so as to require a minimum of new raw material and thus preserve limited natural resources. The illumination apparatus may further comprise an optics module containing an integral heat conducting element and an independ-

ent heat dissipating element, preferably wherein the integral heat conducting element is a component of an optics module that may be serviced and/or replaced separate and independent from the heat dissipating element so as to be environmentally friendly and lower overall maintenance and/or replacement costs for such inventive illumination apparatus.

[0056] While the above description contains much specificity, these should not be construed as limitations on the scope of any embodiment, but as exemplifications of the presently preferred embodiments thereof. Many other ramifications and variations are possible within the teachings of the various embodiments.

[0057] Thus the scope of the invention should be determined by the appended claims and their legal equivalents, and not by the examples given.

Claims

1. An illumination apparatus, said illumination apparatus comprising:

an optics module comprising;

a pendant body, wherein said pendant body comprises a proximal base portion and a distal projection element;
a plurality of light emitting diodes disposed on said projection element of said pendant body;
a lens cover disposed on said pendant body and encapsulating said plurality of light emitting diodes and said projection element;
a driving circuit disposed within said base portion of said pendant body, said base portion defining a cavity in which said driving circuit is disposed, wherein said driving circuit is in electrical communication with said plurality of light emitting diodes; and
a first electrical connector disposed on the proximal surface of said base portion, wherein said first electrical connector is in electrical communication with said driving circuit.

2. The illumination apparatus of claim 1, wherein said base portion further comprises a channel extending from the distal surface of said base portion to said proximal surface of said base portion through which said driving circuit is in electrical communication with said plurality of light emitting diodes.
3. The illumination apparatus of claim 1, wherein said first electrical connector is selected from the group consisting of a button style electrical connector, a leaf spring electrical connector, and a coil spring

electrical connector.

4. The illumination apparatus of claim 1, wherein said projection element of said pendant body comprises a triangular cross section.

5. The illumination apparatus of claim 1, wherein said plurality of light emitting diodes comprises three independent planar light emitting diode modules disposed on said projection element of said pendant body.

6. The illumination apparatus of claim 1, wherein said optics module further comprises:

a first contact board disposed on said proximal surface of said base portion, whereon said first electrical connector is disposed on said first contact board.

7. The illumination apparatus of claim 6, wherein said optics module further comprises:

at least one fastener for securing said first contact board to said proximal surface of said base portion of said pendant body.

8. The illumination apparatus of claim 1, further comprising:

a heat dissipating element comprising a releasable connection to said base portion of said pendant body, wherein said heat dissipating element is reusable and said releasable connection allows for service or replacement of said optics module independent from said heat dissipating element.

9. The illumination apparatus of claim 8, wherein said releasable connection is selected from the group consisting of a threaded connection, a friction fit connection, and a post and groove connection between said heat dissipating element and said base portion of said pendant body.

10. The illumination apparatus of claim 8, wherein said heat dissipating element comprises a plurality of radially projecting fins.

11. The illumination apparatus of claim 8, wherein said heat dissipating element further comprises a second contact board having a second electrical connector disposed on said second contact board, wherein when said releasable connection is established said second electrical connector of said heat dissipating element is in physical and electrical communication with said first electrical connector of said optics module.

12. The illumination apparatus of claim 11, wherein said second electrical connector is selected from the group consisting of a button style electrical connector, a leaf spring electrical connector, and a coil spring electrical connector.

13. The illumination apparatus of claim 11, wherein said second contact board is attached to said heat dissipating element via at least one fixation element.

14. The illumination apparatus of claim 13, wherein said at least one fixation element is selected from the group consisting of at least one tab, at least one screw, at least one rivet, a threaded periphery, adhesive, and bonding.

15. An illumination apparatus, said illumination apparatus comprising:

an optics module comprising;

a pendant body, wherein said pendant body comprises a proximal base portion and a distal projection element;

a plurality of light emitting diodes disposed on said projection element of said pendant body;

a lens cover disposed on said pendant body and encapsulating said plurality of light emitting diodes and said projection element;

a driving circuit disposed within said base portion of said pendant body, said base portion defining a cavity in which said driving circuit is disposed, wherein said driving circuit is in electrical communication with said plurality of light emitting diodes; and

a first electrical connector disposed on the proximal surface of said base portion, wherein said first electrical connector is in electrical communication with said driving circuit;

wherein said base portion further comprises a channel extending from the distal surface of said base portion to said proximal surface of said base portion through which said driving circuit is in electrical communication with said plurality of light emitting diodes; and
a heat dissipating element comprising:

a releasable connection to said base portion of said pendant body, wherein said heat dissipating element is reusable and said releasable connection allows for service or replacement of said optics module independent from said heat dissipating element; and
a second contact board having a second

- electrical connector disposed on said second contact board, wherein when said releasable connection is established said second electrical connector of said heat dissipating element is in physical and electrical communication with said first electrical connector of said optics module. 5
16. The illumination apparatus of claim 15, wherein said first electrical connector and said second electrical connector are independently selected from the group consisting of a button style electrical connector, a leaf spring electrical connector, and a coil spring electrical connector. 10
17. The illumination apparatus of claim 15, wherein said second contact board is attached to said heat dissipating element via at least one fixation element. 15
18. The illumination apparatus of claim 15, wherein said optics module further comprises: 20
- a first contact board disposed on said proximal surface of said base portion upon which said first electrical connector is disposed. 25
19. The illumination apparatus of claim 15, wherein said releasable connection is selected from the group consisting of a threaded connection, a friction fit connection, and a post and groove connection between said heat dissipating element and said base portion of said pendant body. 30
20. An illumination apparatus, said illumination apparatus comprising: 35
- an optics module comprising;
- a pendant body, wherein said pendant body comprises a proximal base portion and a distal projection element; 40
- a plurality of light emitting diodes disposed on said projection element of said pendant body;
- a lens cover disposed on said pendant body and encapsulating said plurality of light emitting diodes and said projection element; 45
- a driving circuit disposed within said base portion of said pendant body, said base portion defining a cavity in which said driving circuit is disposed, wherein said driving circuit is in electrical communication with said plurality of light emitting diodes; and 50
- a first electrical connector disposed on the proximal surface of said base portion, wherein said first electrical connector is in electrical communication with said driving 55

circuit;

wherein said base portion further comprises a channel extending from the distal surface of said base portion to said proximal surface of said base portion through which said driving circuit is in electrical communication with said plurality of light emitting diodes; and
a heat dissipating element comprising:

a releasable connection to said base portion of said pendant body, wherein said heat dissipating element is reusable and said releasable connection allows for service or replacement of said optics module independent from said heat dissipating element, wherein said releasable connection is selected from the group consisting of a threaded connection, a friction fit connection, and a post and groove connection between said heat dissipating element and said base portion of said pendant body; and
a second contact board having a second electrical connector disposed on said second contact board, wherein said second contact board is attached to said heat dissipating element via at least one fixation element and when said releasable connection is established said second electrical connector of said heat dissipating element is in physical and electrical communication with said first electrical connector of said optics module;

wherein said first electrical connector and said second electrical connector are independently selected from the group consisting of a button style electrical connector, a leaf spring electrical connector, and a coil spring electrical connector.

Fig. 1
Prior Art

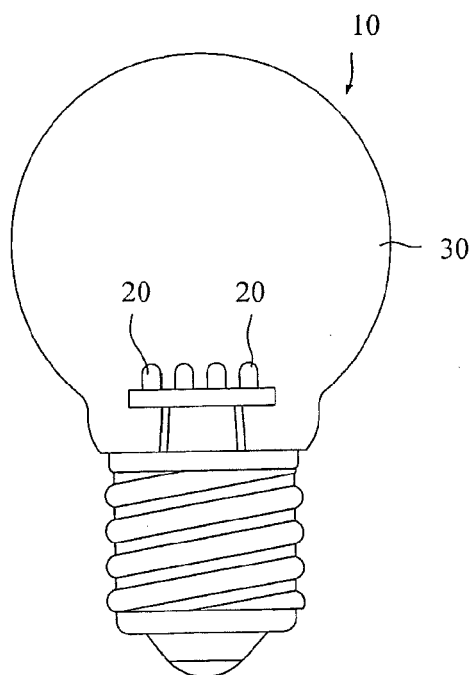


Fig. 2A

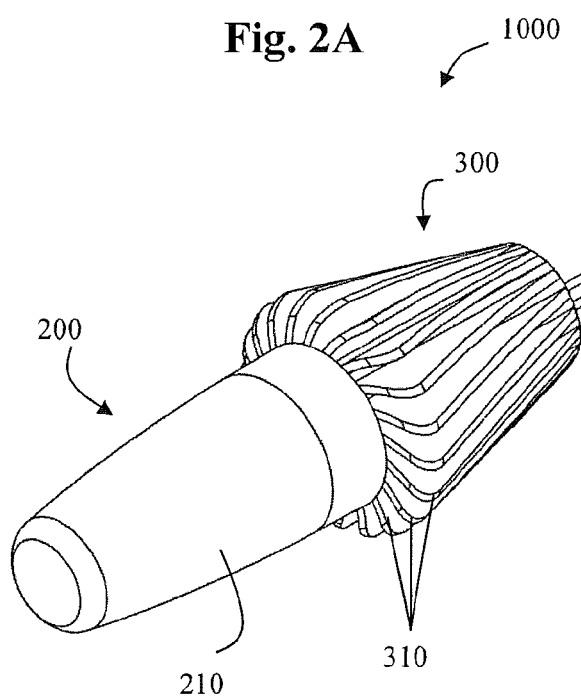


Fig. 2B

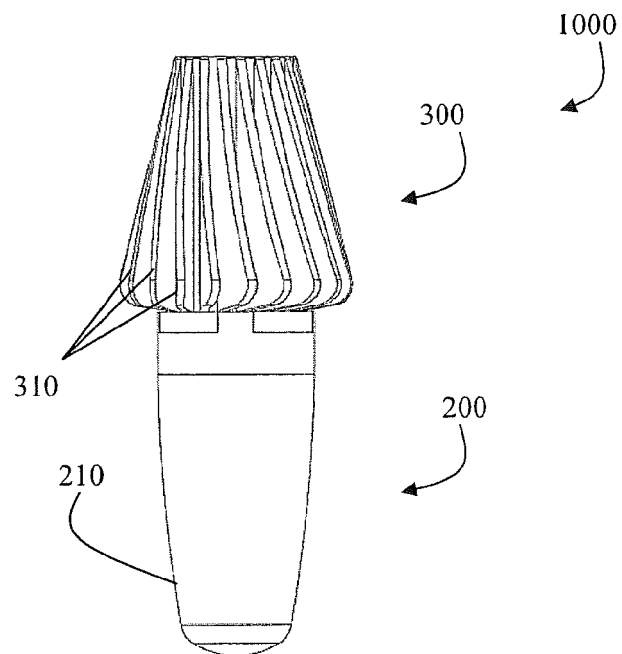


Fig. 2C

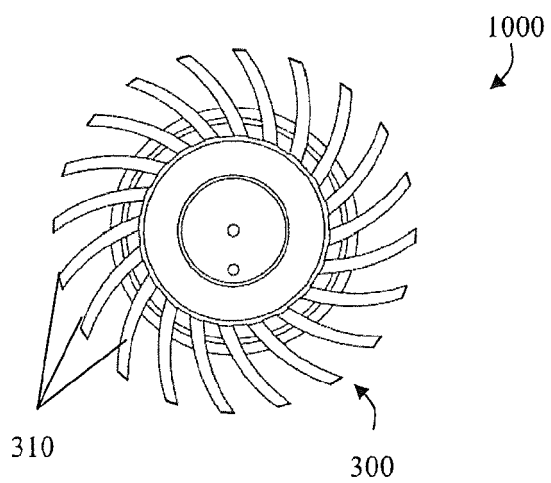


Fig. 2D

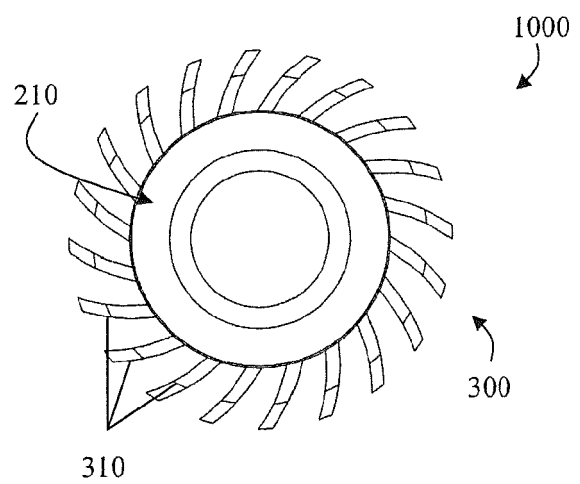


Fig. 3A

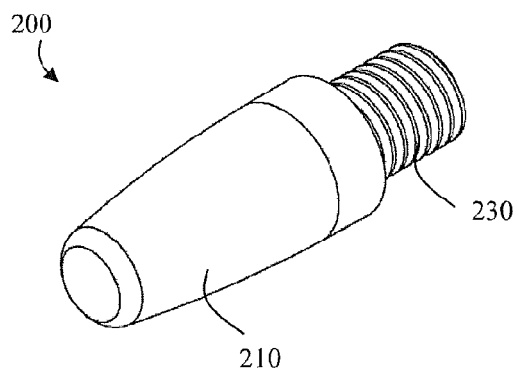


Fig. 3B

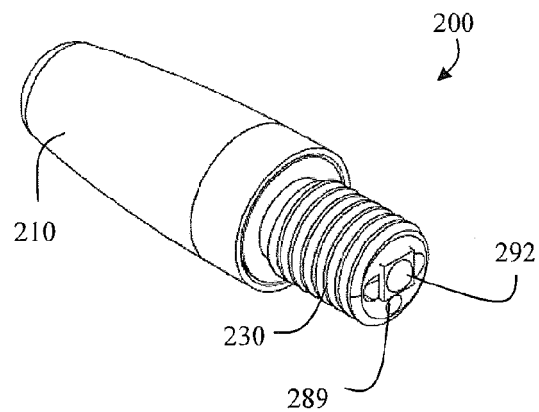


Fig. 3C

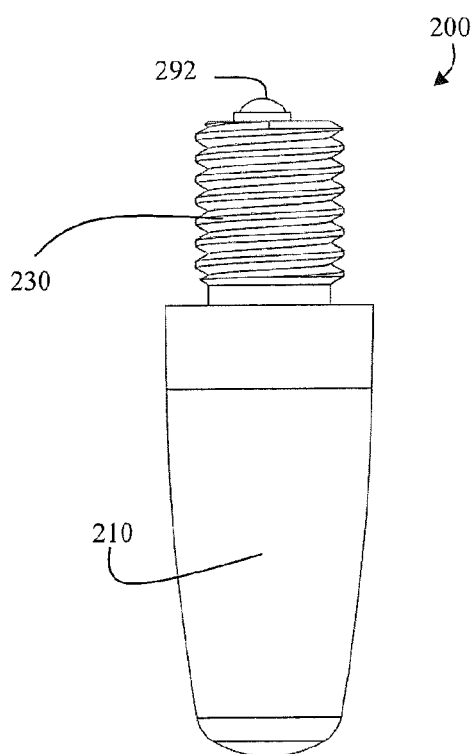


Fig. 3D

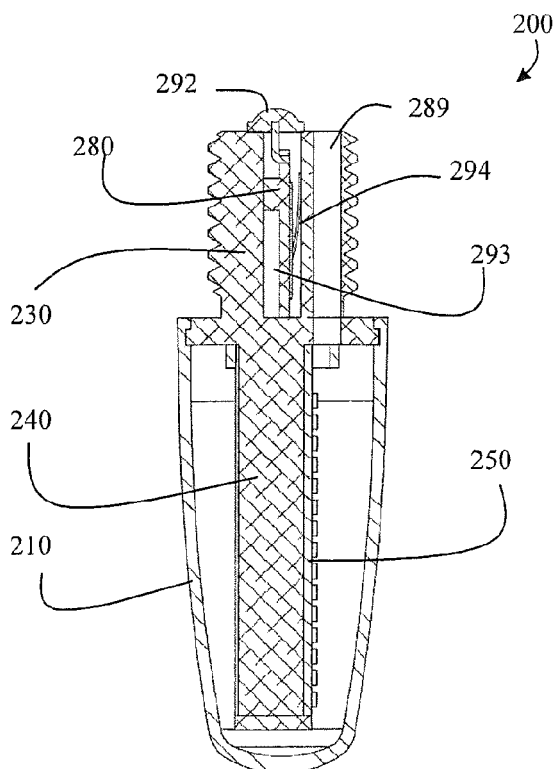


Fig. 3E

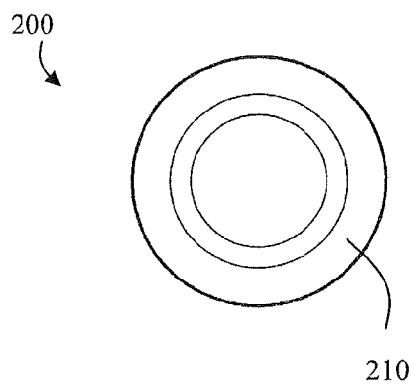


Fig. 3F

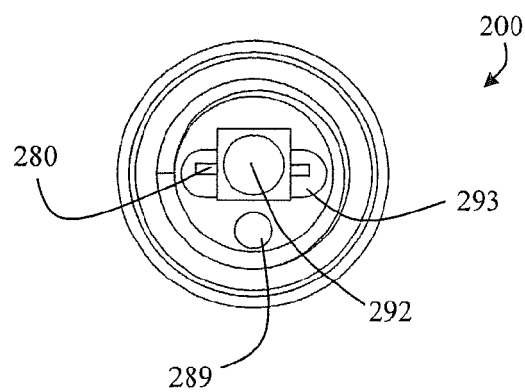


Fig. 4A

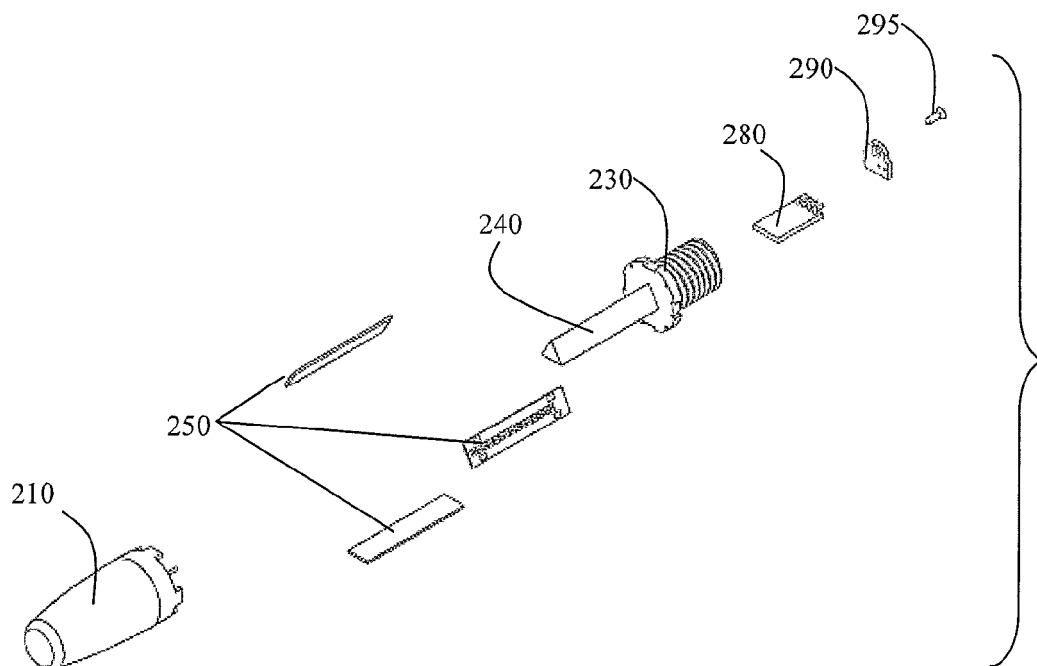


Fig. 4B

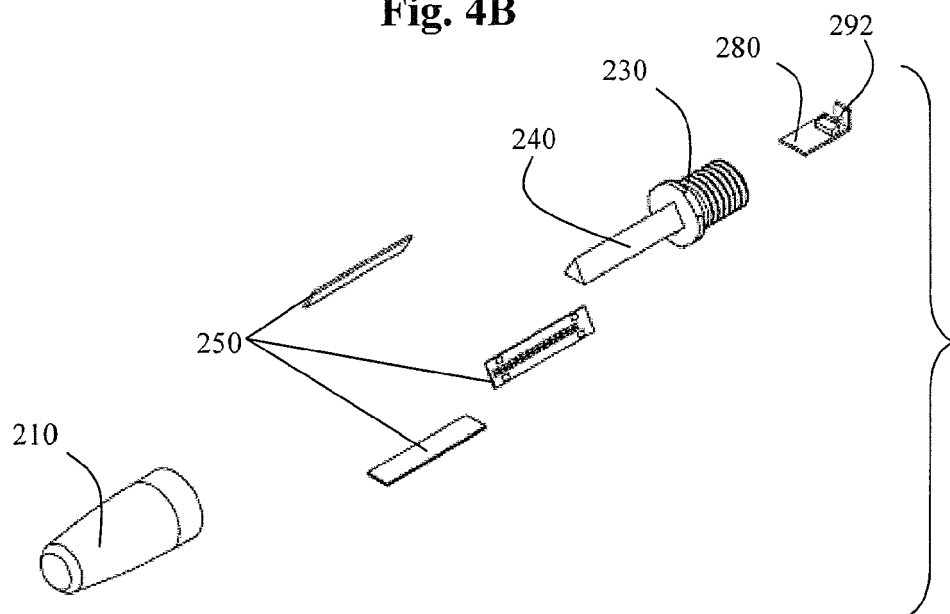


Fig. 5A

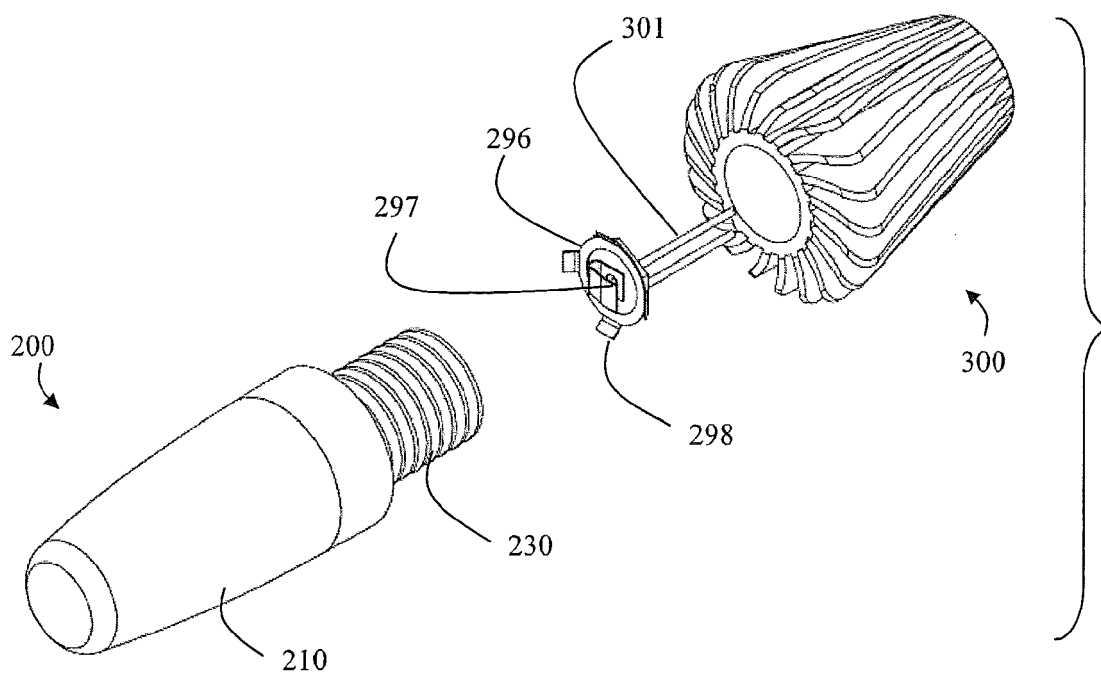


Fig. 5B

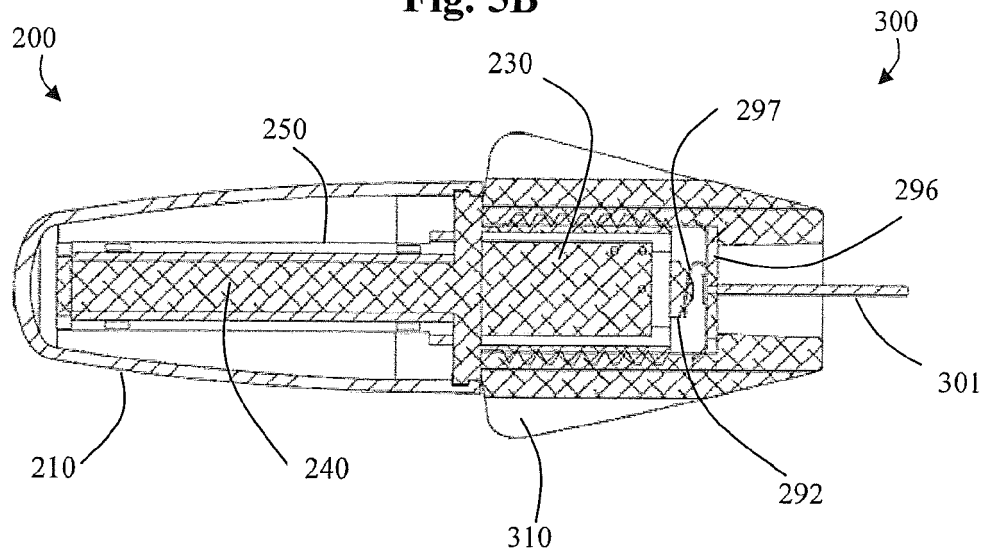
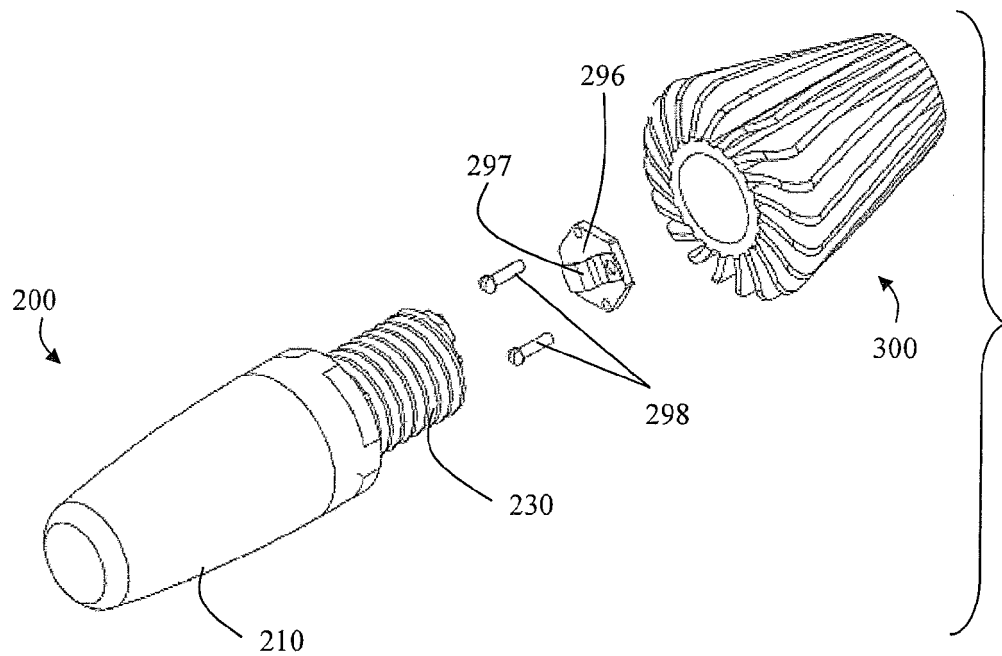


Fig. 6





EUROPEAN SEARCH REPORT

Application Number
EP 09 16 5821

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (IPC)
X	US 2007/159828 A1 (WANG ROBERT [TW]) 12 July 2007 (2007-07-12)	1-7	INV. F21K7/00 F21V29/00
Y	* paragraph [0011]; figure 2 *	8-10	
Y	US 2008/055909 A1 (LI JIA-HAO [TW]) 6 March 2008 (2008-03-06) * paragraphs [0004], [0005]; figure 3 *	8-10	
X	US 2008/062703 A1 (CAO DENSEN [US]) 13 March 2008 (2008-03-13) * figure 2 * * paragraph [0021] *	1-7	
The present search report has been drawn up for all claims			TECHNICAL FIELDS SEARCHED (IPC)
			F21K F21V
Place of search		Date of completion of the search	Examiner
The Hague		20 August 2009	Amerongen, Wim
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EP 09 16 5821

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20-08-2009

Patent document cited in search report	Publication date	Patent family member(s)	Publication date
US 2007159828 A1	12-07-2007	NONE	
US 2008055909 A1	06-03-2008	NONE	
US 2008062703 A1	13-03-2008	NONE	

REFERENCES CITED IN THE DESCRIPTION

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- US 7226189 B [0013]
- US 20060050514 A [0013]
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